

GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Cirlex or equivalent Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- △ 9 Socket lid screw: Socket head cap, Alloy steel with oxide finish, 0-80 fine thread, 4.76mm long.
- △ 10 Insulation Plate: FR4/G10, 1.59mm thick.
- △ 11 Backing Plate: Black anodized Aluminum, Thickness = 6.35mm.
- △ 12 IC Guide: FR4

SG-BGA-6261 Drawing

Status: Released

Scale: -

Rev: A

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Tele: (952) 229-8223
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Drawing: Umer Qureshi

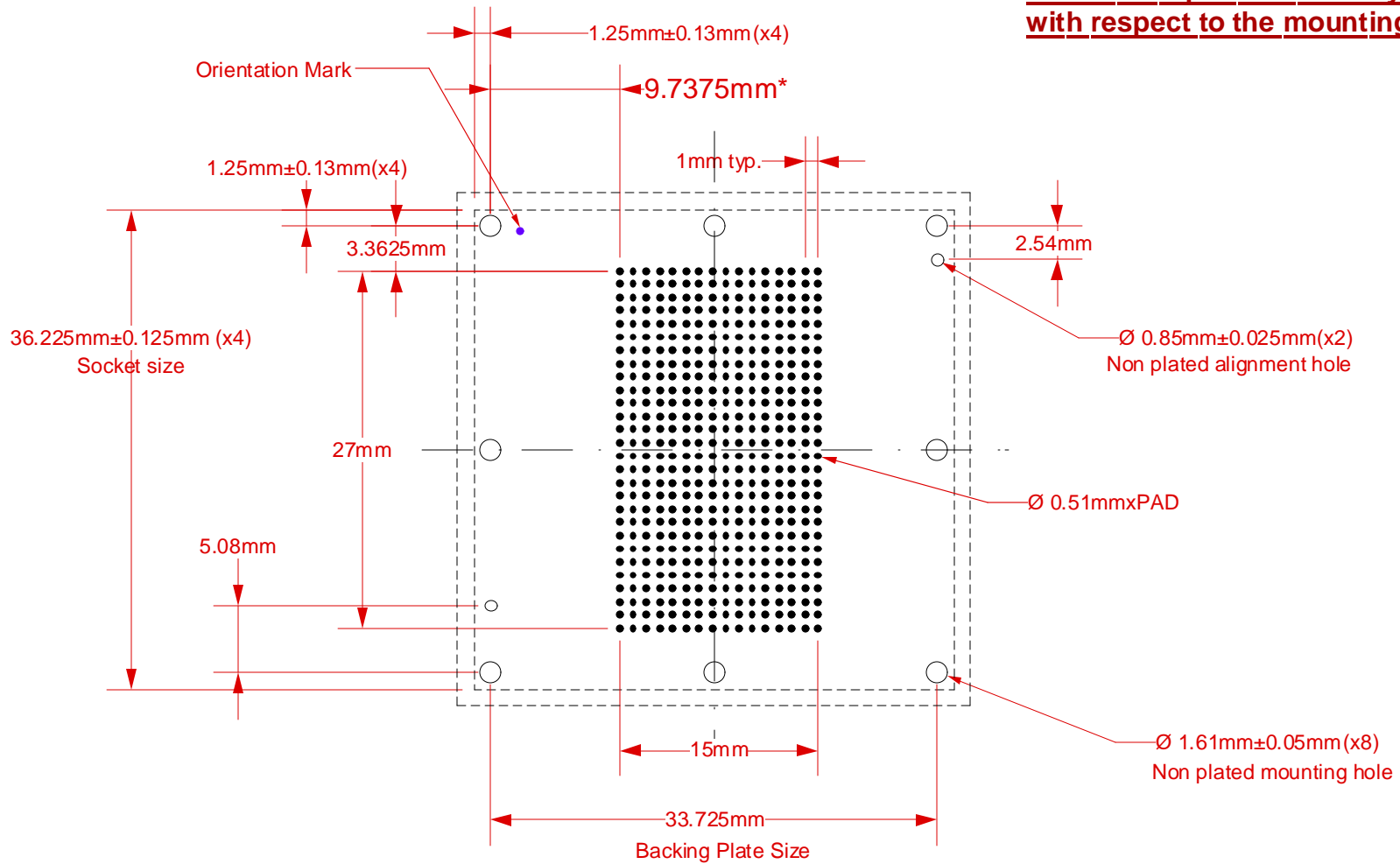
Date: 03/14/08

File: SG-BGA-6261 Dwg

Modified:

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View




***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

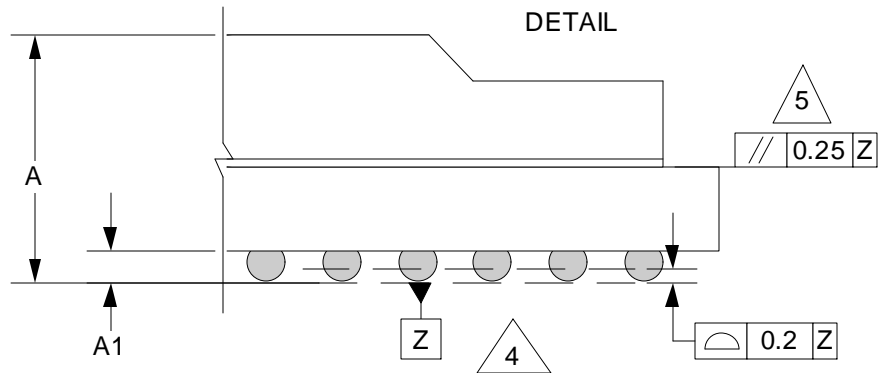
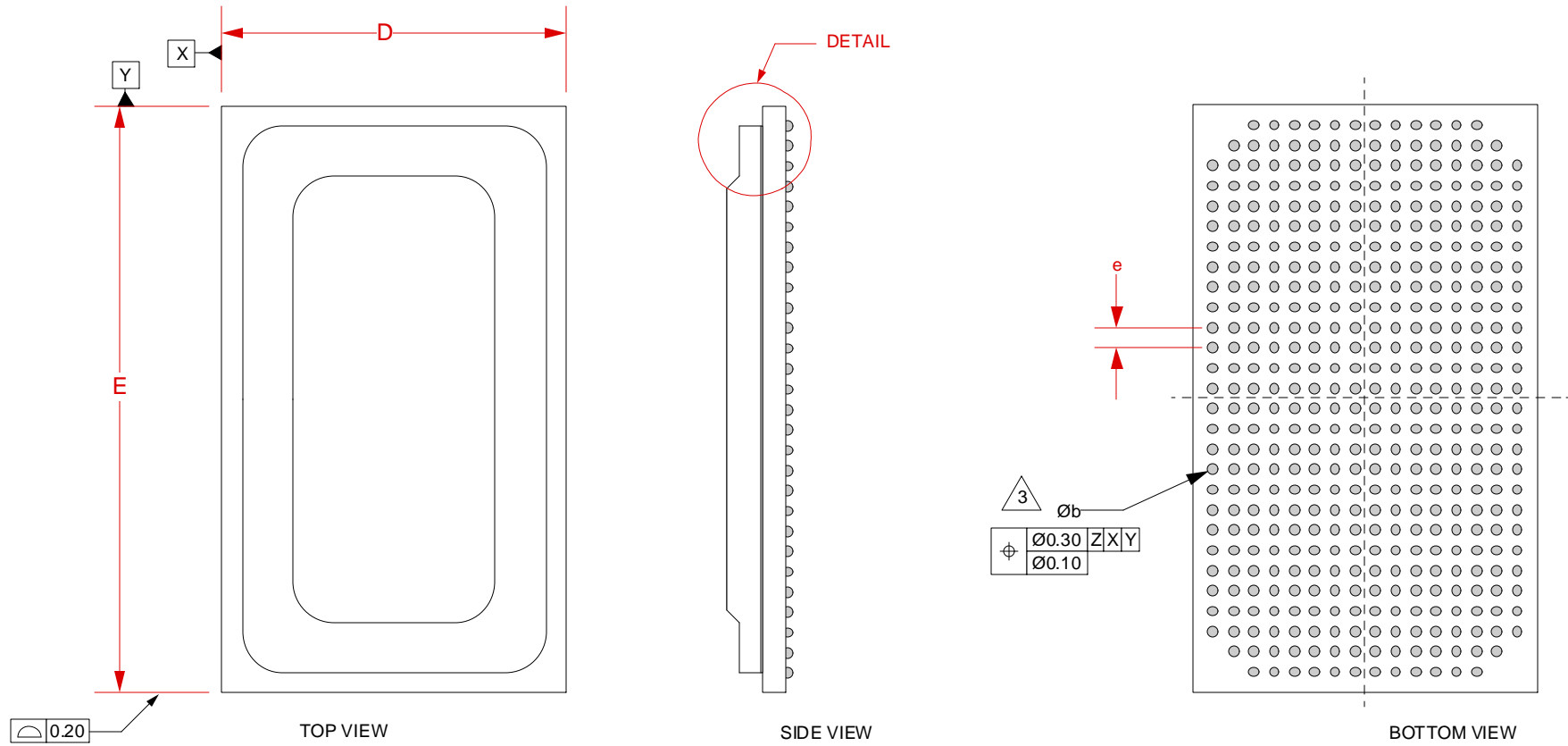
Target PCB Recommendations

Total thickness: 2.4mm min.
 Plating: Gold or Solder finish
 PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001''$] unless stated otherwise.


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	<p>Drawing: Umer Qureshi</p>	<p>Date: 03/14/08</p>		<p>Modified:</p>
	<p>File: SG-BGA-6261 Dwg</p>			



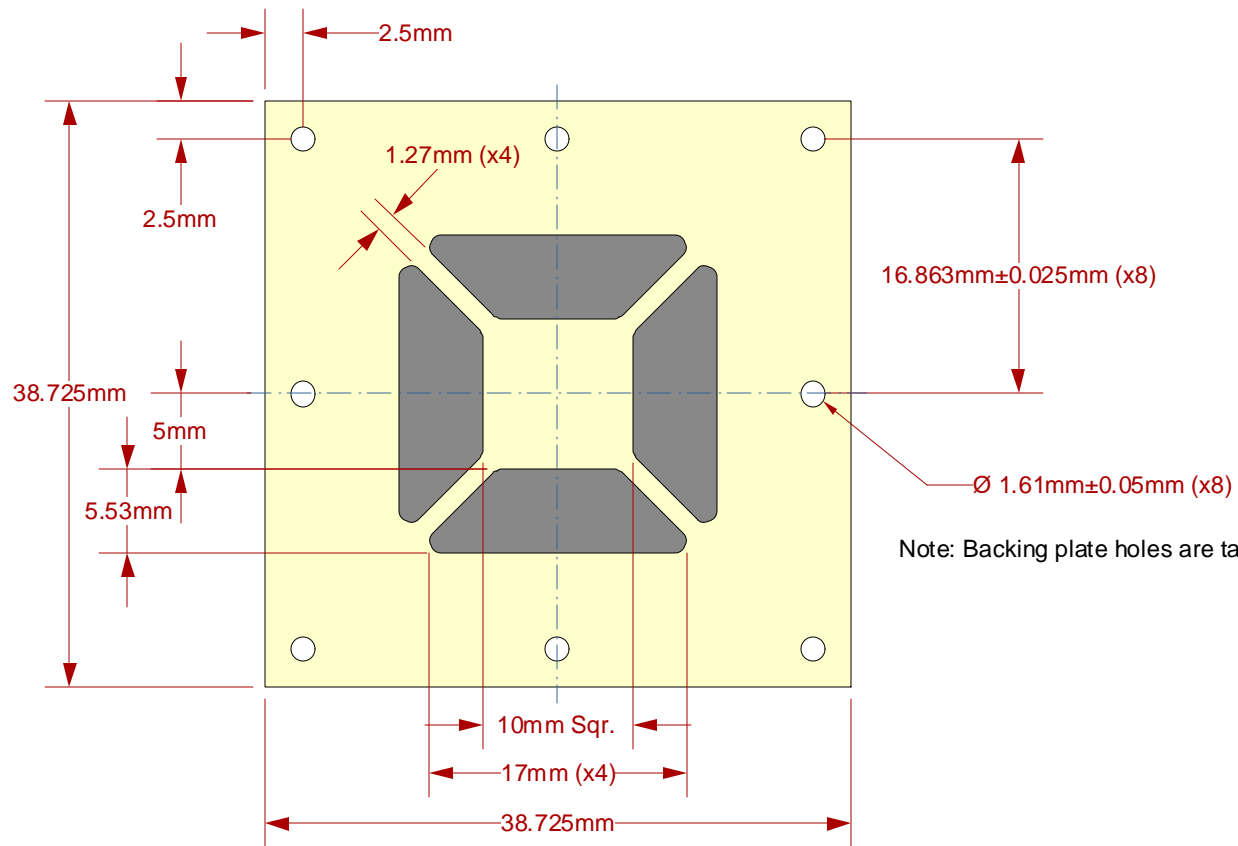
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A	3.25	3.56
A1	0.40	0.60
b	0.50	0.70
D	17.00 BSC	
E	29.00 BSC	
e	1.0 BSC	

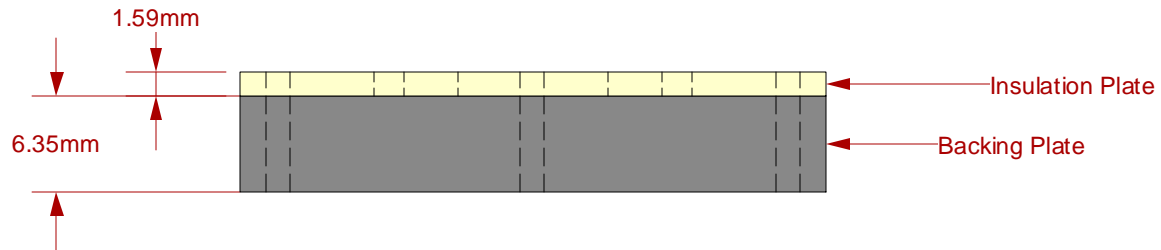
Array 16x28

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Top View




Side View



Description: Insulation Plate and Backing Plate

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All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)